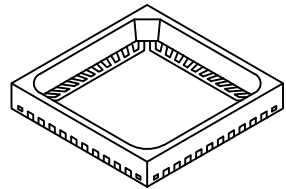
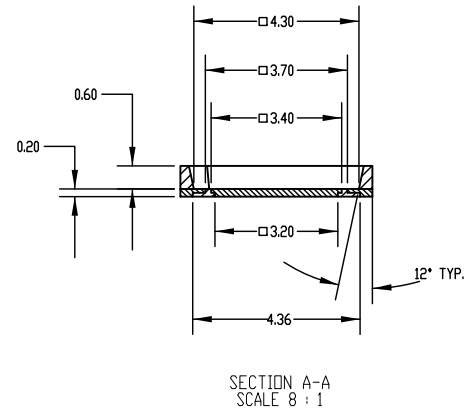
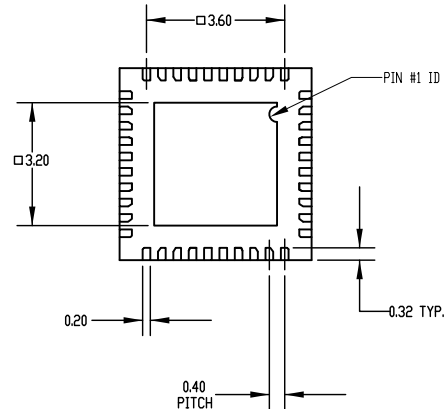
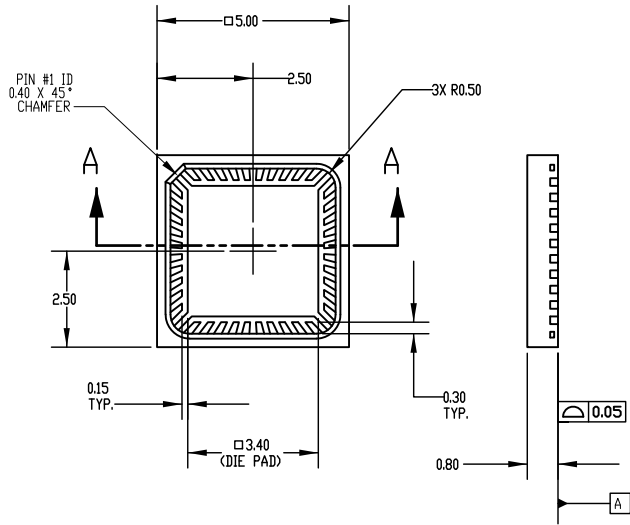


SSM P/N QFN04006

REVISIONS					
ZONE	REV.	DESCRIPTION	DATE	APPROVED	DCN NO.
	A	ORIGINAL RELEASE	12/21/2020	SS	



NOTES:

- MATERIALS:
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT SPECTRUM FOR DETAILS.
- LEAD FRAME FINISH: ENEPIG (Ni/Pd/Au)
ELECTROLESS NICKEL: 1.27 - 4.51 MICRONS (50 -177 micro-inches)
ELECTROLESS PALLADIUM: 15 - 51 MICRON (6 - 20 micro-inches)
GOLD PLATE: 10 - 20 MICRON (4 - 8 micro-inches)
- BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)
- PACKAGE MISMATCH: BODY OFFSET TO LEAD FRAME = 0.076mm MAX.
- UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.
- PACKAGE CONFORMS TO JEDEC MO-220

		UNLESS OTHERWISE SPECIFIED		NAME	DATE	Spectrum Semiconductor Materials, Inc. 155 Nicholson Lane San Jose, CA 95134 PH: (408) 435.5555 Fx (408) 435.8226	
		DIMENSIONS ARE IN MILLIMETERS		DRAWN	S. Suen		12/21/20
		TOLERANCES ARE:		CHECKED	S. Suen		12/21/20
		ANGULAR: ±1.0 degree		ENG APPR.	S. Suen		12/21/20
		X = ±0.13					
		XX=0.05					
		MATERIAL		COMMENTS:		TITLE:	
		SEE NOTE 1				QP-QFN40-5MM-0.40MM	
		FINISH				WITH Ni/Pd/Au PLATING	
		SEE NOTE 2				SIZE DWG. NO.	
NEXT ASSY		USED ON				501404	
APPLICATION		DO NOT SCALE DRAWING				REV	
						A	
				SCALE: 8:1		WEIGHT:	
						SHEET 1 OF 1	

